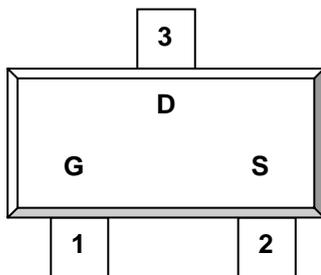


# ST2301A

## DESCRIPTION

ST2301A is the P-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management, other battery powered circuits, and low in-line power loss are required. The product is in a very small outline surface mount package.

## PIN CONFIGURATION SOT-23

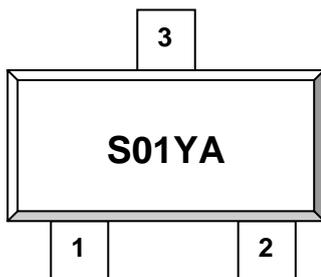


1. Gate 2. Source 3. Drain

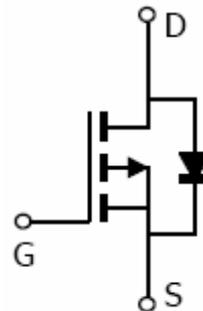
## FEATURE

- -20V/-2.8A,  $R_{DS(ON)} = 80m\Omega$  (Typ.)  
@ $V_{GS} = -4.5V$
- -20V/-2.0A,  $R_{DS(ON)} = 120m\Omega$   
@ $V_{GS} = -2.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

## PART MARKING SOT-23



Y: Year Code A: Process Code



## ORDERING INFORMATION

Part Number	Package	Part Marking
ST2301SRG	SOT-23	S01YA

※ Process Code : A ~ Z ; a ~ z

※ ST2301SRG : S : SOT23 R : Tape Reel ; G : Pb - Free

**ST2301A**
**ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted )**

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V <sub>DSS</sub>	-20	V
Gate-Source Voltage		V <sub>GSS</sub>	±12	V
Continuous Drain Current (T <sub>J</sub> =150°C)	T <sub>A</sub> =25°C T <sub>A</sub> =70°C	I <sub>D</sub>	-3.0 -2.0	A
Pulsed Drain Current		I <sub>DM</sub>	-10	A
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	-1.6	A
Power Dissipation	T <sub>A</sub> =25°C T <sub>A</sub> =70°C	P <sub>D</sub>	1.25 0.8	W
Operation Junction Temperature		T <sub>J</sub>	150	°C
Storage Temperature Range		T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient		R <sub>θJA</sub>	120	°C/W

**ST2301A**
**ELECTRICAL CHARACTERISTICS ( Ta = 25°C Unless otherwise noted )**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.45		-1.5	V
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 12V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V$			-1	$\mu A$
		$V_{DS}=-20V, V_{GS}=0V$ $T_J=55^\circ C$			-10	
On-State Drain Current	$I_{D(on)}$	$V_{DS}\leq -5V, V_{GS}=-4.5V$ $V_{DS}\leq -5V, V_{GS}=-2.5V$	-6 -3			A
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=-2.5V, I_D=-2.0A$ $V_{GS}=-4.5V, I_D=-2.8A$		0.080 0.120		$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS}=-5V, I_D=-2.8V$		6.5		S
Diode Forward Voltage	$V_{SD}$	$I_S=-1.6A, V_{GS}=0V$		-0.8	-1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=-6V$ $V_{GS}=-4.5V$ $I_D=-2.8A$		5.8	10	nC
Gate-Source Charge	$Q_{gs}$			0.85		
Gate-Drain Charge	$Q_{gd}$			1.7		
Input Capacitance	$C_{iss}$	$V_{DS}=-6V$ $V_{GS}=0V$ $F=1MHz$		415		pF
Output Capacitance	$C_{oss}$			223		
Reverse Transfer Capacitance	$C_{rss}$			87		
Turn-On Time	$t_{d(on)}$ $t_r$	$V_{DD}=-6V$ $R_L=6\Omega$ $I_D=-1A$ $V_{GEN}=-4.5V$ $R_G=6\Omega$		13	25	nS
				36	60	
Turn-Off Time	$t_{d(off)}$ $t_f$			42	70	
				34	60	